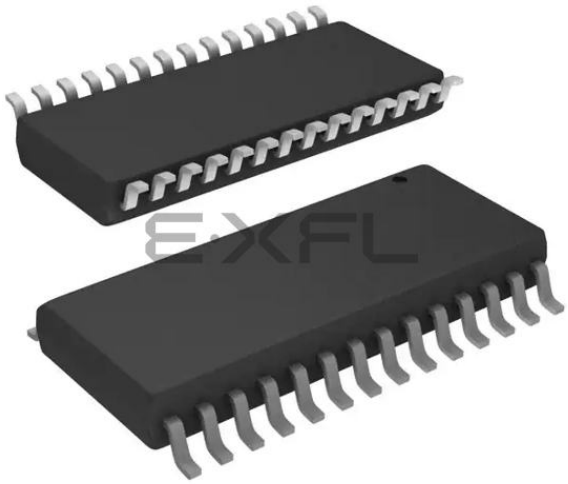

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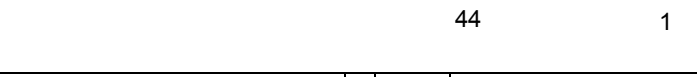
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	19
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx250f128b-50i-so

TABLE 9: PIN NAMES FOR 44-PIN GENERAL PURPOSE DEVICES

44-PIN QFN (TOP VIEW)(1,2,3,5)

PIC32MX110F016D
PIC32MX120F032D
PIC32MX130F064D
PIC32MX130F256D
PIC32MX150F128D
PIC32MX170F256D



Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/CTED11/PMD2/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/PMD1/RB11	31	OSC2/CLKO/RPA3/RA3
10	AN12/PMD0/RB12	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4(4)/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4(4)/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14	36	RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/RA0	41	PGED3/RPB5/PMD7/RB5
20	VREF-/CVREF-/AN1/RPA1/CTED2/RA1	42	PGEC3/RPB6/PMD6/RB6
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.
2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.
3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
4: This pin function is not available on PIC32MX110F016D and PIC32MX120F032D devices.
5: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
PMA0	7	10	8	3	I/O	TTL/ST	Parallel Master Port Address bit 0 input (Buffered Slave modes) and output (Master modes)
PMA1	9	12	10	2	I/O	TTL/ST	Parallel Master Port Address bit 1 input (Buffered Slave modes) and output (Master modes)
PMA2		—	—	27	O	—	Parallel Master Port address (Demultiplexed Master modes)
PMA3		—	—	38	O	—	
PMA4		—	—	37	O	—	
PMA5		—	—	4	O	—	
PMA6		—	—	5	O	—	
PMA7		—	—	13	O	—	
PMA8		—	—	32	O	—	
PMA9		—	—	35	O	—	
PMA10		—	—	12	O	—	
PMCS1	23	26	29	15	O	—	Parallel Master Port Chip Select 1 strobe
PMD0	20(2)	23(2)	26(2)	10(2)	I/O	TTL/ST	Parallel Master Port data (Demultiplexed Master mode) or address/data (Multiplexed Master modes)
	1(3)	4(3)	35(3)	21(3)			
PMD1	19(2)	22(2)	25(2)	9(2)	I/O	TTL/ST	
	2(3)	5(3)	36(3)	22(3)			
PMD2	18(2)	21(2)	24(2)	8(2)	I/O	TTL/ST	
	3(3)	6(3)	1(3)	23(3)			
PMD3	15	18	19	1	I/O	TTL/ST	
PMD4	14	17	18	44	I/O	TTL/ST	
PMD5	13	16	17	43	I/O	TTL/ST	
PMD6	12(2)	15(2)	16(2)	42(2)	I/O	TTL/ST	
	28(3)	3(3)	34(3)	20(3)			
PMD7	11(2)	14(2)	15(2)	41(2)	I/O	TTL/ST	
	27(3)	2(3)	33(3)	19(3)			
PMRD	21	24	27	11	O	—	Parallel Master Port read strobe
PMWR	22(2)	25(2)	28(2)	14(2)	O	—	Parallel Master Port write strobe
	4(3)	7(3)	2(3)	24(3)			
VBUS	12(3)	15(3)	16(3)	42(3)	I	Analog	USB bus power monitor
VUSB3V3	20(3)	23(3)	26(3)	10(3)	P	—	USB internal transceiver supply. This pin must be connected to VDD.
VBUSON	22(3)	25(3)	28(3)	14(3)	O	—	USB Host and OTG bus power control output
D+	18(3)	21(3)	24(3)	8(3)	I/O	Analog	USB D+
D-	19(3)	22(3)	25(3)	9(3)	I/O	Analog	USB D-

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source.For detailed information, refer to **Section 3. "Memory Organization"** (DS60001115), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers provide 4 GB unified virtual memory address space. All memory regions, including program, data memory, Special Function Registers (SFRs), and Configuration registers, reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX1XX/2XX 28/36/44-pin Family devices to execute from data memory.

Key features include:

- 32-bit native data width
- Separate User (KUSEG) and Kernel (KSEG0/KSEG1) mode address space
- Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit
- Cacheable (KSEG0) and non-cacheable (KSEG1) address regions

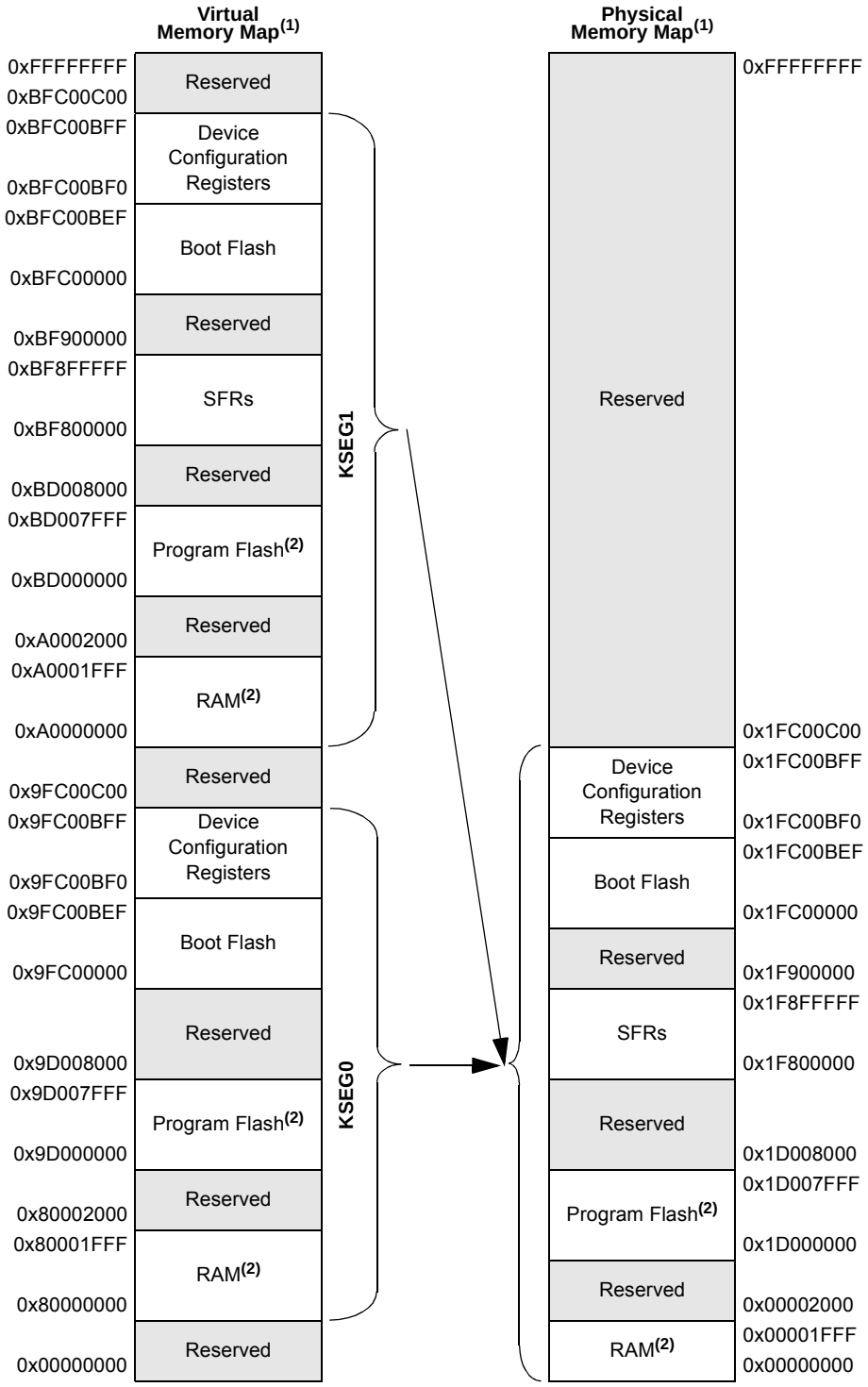
4.1 PIC32MX1XX/2XX 28/36/44-pin Family Memory Layout

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers implement two address schemes: virtual and physical. All hardware resources, such as program memory, data memory and peripherals, are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by bus master peripherals, such as DMA and the Flash controller, that access memory independently of the CPU.

The memory maps for the PIC32MX1XX/2XX 28/36/44-pin Family devices are illustrated in Figure 4-1 through Figure 4-6.

Table 4-1 provides SFR memory map details.

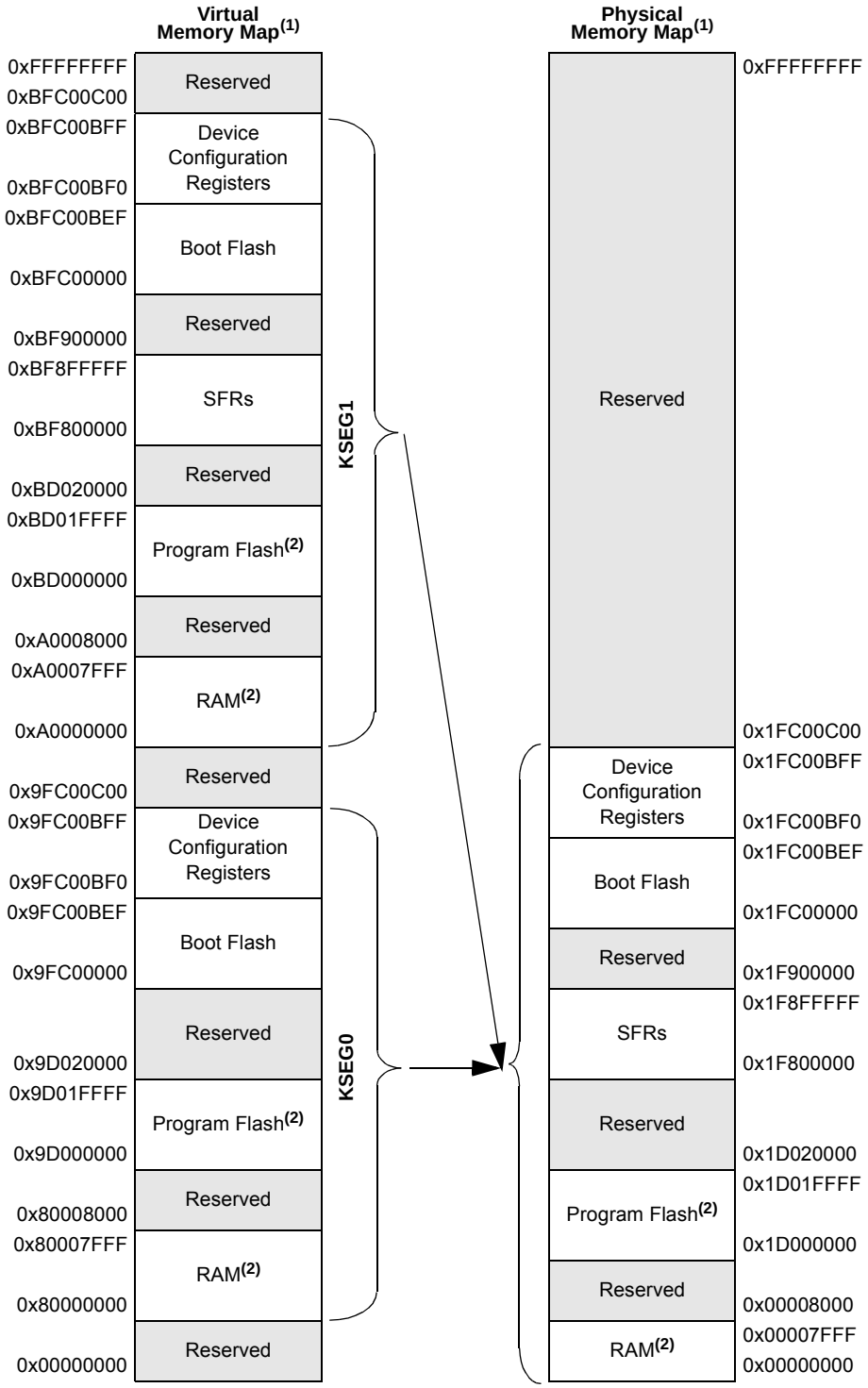
FIGURE 4-2: MEMORY MAP ON RESET FOR PIC32MX120/220 DEVICES (8 KB RAM, 32 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

FIGURE 4-4: MEMORY MAP ON RESET FOR PIC32MX150/250 DEVICES (32 KB RAM, 128 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 8-3: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	RODIV<14:8>(1,3)						
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	RODIV<7:0>(1,3)							
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R-0, HS, HC
	ON	—	SIDL	OE	RSLP(2)	—	DIVSWEN	ACTIVE
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	ROSEL<3:0>(1)			

Legend:	HC = Hardware Clearable	HS = Hardware Settable	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Unimplemented:** Read as '0'

bit 30-16 **RODIV<14:0>** Reference Clock Divider bits(1,3)

The value selects the reference clock divider bits. See Figure 8-1 for information.

bit 15 **ON:** Output Enable bit

1 = Reference Oscillator module is enabled
0 = Reference Oscillator module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Peripheral Stop in Idle Mode bit

1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **OE:** Reference Clock Output Enable bit

1 = Reference clock is driven out on REFCLKO pin
0 = Reference clock is not driven out on REFCLKO pin

bit 11 **RSLP:** Reference Oscillator Module Run in Sleep bit(2)

1 = Reference Oscillator module output continues to run in Sleep
0 = Reference Oscillator module output is disabled in Sleep

bit 10 **Unimplemented:** Read as '0'

bit 9 **DIVSWEN:** Divider Switch Enable bit

1 = Divider switch is in progress
0 = Divider switch is complete

bit 8 **ACTIVE:** Reference Clock Request Status bit

1 = Reference clock request is active
0 = Reference clock request is not active

bit 7-4 **Unimplemented:** Read as '0'

Note 1: The ROSEL and RODIV bits should not be written while the ACTIVE bit is '1', as undefined behavior may result.

2: This bit is ignored when the ROSEL<3:0> bits = 0000 or 0001.

3: While the ON bit is set to '1', writes to these bits do not take effect until the DIVSWEN bit is also set to '1'.

REGISTER 10-11: U1CON: USB CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-x	R-x	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	JSTATE	SE0	PKTDIS(4) / TOKBUSY(1,5)	USBRST	HOSTEN(2)	RESUME(3)	PPBRST	USBEN(4) / SOFEN(5)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **JSTATE:** Live Differential Receiver JSTATE flag bit
1 = JSTATE was detected on the USB
0 = No JSTATE was detected

bit 6 **SE0:** Live Single-Ended Zero flag bit
1 = Single-Ended Zero was detected on the USB
0 = No Single-Ended Zero was detected

bit 5 **PKTDIS:** Packet Transfer Disable bit(4)
1 = Token and packet processing is disabled (set upon SETUP token received)
0 = Token and packet processing is enabled

TOKBUSY: Token Busy Indicator bit(1,5)
1 = Token is being executed by the USB module
0 = No token is being executed

bit 4 **USBRST:** Module Reset bit(5)
1 = USB reset generated
0 = USB reset terminated

bit 3 **HOSTEN:** Host Mode Enable bit(2)
1 = USB host capability is enabled
0 = USB host capability is disabled

bit 2 **RESUME:** RESUME Signaling Enable bit(3)
1 = RESUME signaling is activated
0 = RESUME signaling is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

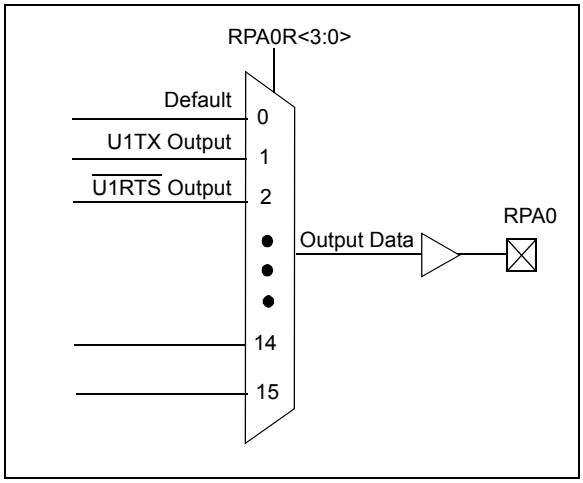
5: Host mode.

11.3.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the PPS options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPnR registers (Register 11-2) are used to control output mapping. Like the [*pin name*]R registers, each register contains sets of 4 bit fields. The value of the bit field corresponds to one of the peripherals, and that peripheral's output is mapped to the pin (see Table 11-2 and Figure 11-3).

A null output is associated with the output register reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 11-3: EXAMPLE OF MULTIPLEXING OF REMAPPABLE OUTPUT FOR RPA0



11.3.6 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to the peripheral map:

- Control register lock sequence
- Configuration bit select lock

11.3.6.1 Control Register Lock Sequence

Under normal operation, writes to the RPnR and [*pin name*]R registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the Configuration bit, IOLOCK (CFGCON<13>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear the IOLOCK bit, an unlock sequence must be executed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

11.3.6.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPnR and [*pin name*]R registers. The Configuration bit, IOL1WAY (DEVCFG3<29>), blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure does not execute, and the PPS control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session.

REGISTER 12-1: T1CON: TYPE A TIMER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R-0	U-0	U-0	U-0
	ON(1)	—	SIDL	TWDIS	TWIP	—	—	—
7:0	R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
	TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Timer On bit(1)
- 1 = Timer is enabled
- 0 = Timer is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue module operation when the device enters Idle mode
- 0 = Continue module operation when the device enters Idle mode

bit 12 **TWDIS:** Asynchronous Timer Write Disable bit
- 1 = Writes to Timer1 are ignored until pending write operation completes
- 0 = Back-to-back writes are enabled (Legacy Asynchronous Timer functionality)

bit 11 **TWIP:** Asynchronous Timer Write in Progress bit

In Asynchronous Timer mode:
- 1 = Asynchronous write to the Timer1 register in progress
- 0 = Asynchronous write to Timer1 register is complete

In Synchronous Timer mode:
This bit is read as '0'.

bit 10-8 **Unimplemented:** Read as '0'

bit 7 **TGATE:** Timer Gated Time Accumulation Enable bit

When TCS = 1:
This bit is ignored.

When TCS = 0:
- 1 = Gated time accumulation is enabled
- 0 = Gated time accumulation is disabled

bit 6 **Unimplemented:** Read as '0'

bit 5-4 **TCKPS<1:0>:** Timer Input Clock Prescale Select bits
- 11 = 1:256 prescale value
- 10 = 1:64 prescale value
- 01 = 1:8 prescale value
- 00 = 1:1 prescale value

Note 1: When using 1:1 PBCmLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

NOTES:

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits(2)

11111111 = Alarm will trigger 256 times
•
•
•
00000000 = Alarm will trigger one time
The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note:	This register is reset only on a Power-on Reset (POR).

22.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

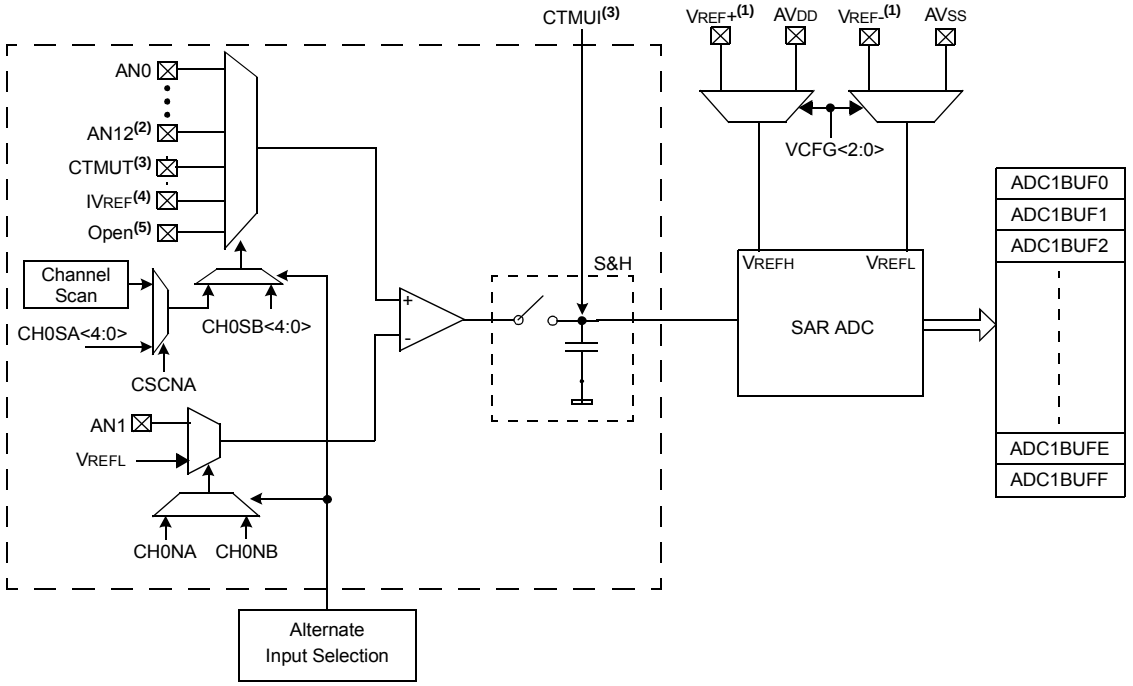
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed
- Up to 13 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during Sleep and Idle modes

A block diagram of the 10-bit ADC is illustrated in Figure 22-1. Figure 22-2 illustrates a block diagram of the ADC conversion clock period. The 10-bit ADC has up to 13 analog input pins, designated AN0-AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

FIGURE 22-1: ADC1 MODULE BLOCK DIAGRAM



Note 1: VREF+ and VREF- inputs can be multiplexed with other analog inputs.

2: AN8 is only available on 44-pin devices. AN6, AN7, and AN12 are not available on 28-pin devices.

3: Connected to the CTMU module. See **Section 25.0 "Charge Time Measurement Unit (CTMU)"** for more information.

4: Internal precision voltage reference (1.2V).

5: This selection is only used with CTMU capacitive and time measurement.

REGISTER 22-2: AD1CON2: ADC CONTROL REGISTER 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0	U-0
	VCFG<2:0>			OFFCAL	—	CSCNA	—	—
7:0	R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BUFS	—	SMPI<3:0>				BUFM	ALTS

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-13 **VCFG<2:0>:** Voltage Reference Configuration bits

	VREFH	VREFL
000	AVDD	AVss
001	External VREF+ pin	AVSS
010	AVDD	External VREF- pin
011	External VREF+ pin	External VREF- pin
1xx	AVDD	AVSS

bit 12 **OFFCAL:** Input Offset Calibration Mode Select bit
1 = Enable Offset Calibration mode
Positive and negative inputs of the sample and hold amplifier are connected to VREFL
0 = Disable Offset Calibration mode
The inputs to the sample and hold amplifier are controlled by AD1CHS or AD1CSSL

bit 11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Input Scan Select bit
1 = Scan inputs
0 = Do not scan inputs

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **BUFS:** Buffer Fill Status bit
Only valid when BUFM = 1.
1 = ADC is currently filling buffer 0x8-0xF, user should access data in 0x0-0x7
0 = ADC is currently filling buffer 0x0-0x7, user should access data in 0x8-0xF

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **SMPI<3:0>:** Sample/Convert Sequences Per Interrupt Selection bits
1111 = Interrupts at the completion of conversion for each 16th sample/convert sequence
1110 = Interrupts at the completion of conversion for each 15th sample/convert sequence
•
•
•
0001 = Interrupts at the completion of conversion for each 2nd sample/convert sequence
0000 = Interrupts at the completion of conversion for each sample/convert sequence

bit 1 **BUFM:** ADC Result Buffer Mode Select bit
1 = Buffer configured as two 8-word buffers, ADC1BUF7-ADC1BUF0, ADC1BUFF-ADCBUF8
0 = Buffer configured as one 16-word buffer ADC1BUFF-ADC1BUF0

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses Sample A input multiplexer settings for first sample, then alternates between Sample B and Sample A input multiplexer settings for all subsequent samples
0 = Always use Sample A input multiplexer settings

26.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. "Power-Saving Features"** (DS60001130), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This section describes power-saving features for the PIC32MX1XX/2XX 28/36/44-pin Family. The PIC32 devices offer a total of nine methods and modes, organized into two categories, that allow the user to balance power consumption with device performance. In all of the methods and modes described in this section, power-saving is controlled by software.

26.1 Power Saving with CPU Running

When the CPU is running, power consumption can be controlled by reducing the CPU clock frequency, lowering the PBCLK and by individually disabling modules. These methods are grouped into the following categories:

- FRC Run mode: the CPU is clocked from the FRC clock source with or without postscalers
- LPRC Run mode: the CPU is clocked from the LPRC clock source
- SOSC Run mode: the CPU is clocked from the SOSC clock source

In addition, the Peripheral Bus Scaling mode is available where peripherals are clocked at the programmable fraction of the CPU clock (SYSCLK).

26.2 CPU Halted Methods

The device supports two power-saving modes, Sleep and Idle, both of which Halt the clock to the CPU. These modes operate with all clock sources, as follows:

- POSC Idle mode: the system clock is derived from the POSC. The system clock source continues to operate. Peripherals continue to operate, but can optionally be individually disabled.
- FRC Idle mode: the system clock is derived from the FRC with or without postscalers. Peripherals continue to operate, but can optionally be individually disabled.
- SOSC Idle mode: the system clock is derived from the SOSC. Peripherals continue to operate, but can optionally be individually disabled.
- LPRC Idle mode: the system clock is derived from the LPRC. Peripherals continue to operate, but can optionally be individually disabled. This is the lowest power mode for the device with a clock running.
- Sleep mode: the CPU, the system clock source and any peripherals that operate from the system clock source are Halted. Some peripherals can operate in Sleep using specific clock sources. This is the lowest power mode for the device.

26.3 Power-Saving Operation

Peripherals and the CPU can be Halted or disabled to further reduce power consumption.

26.3.1 SLEEP MODE

Sleep mode has the lowest power consumption of the device power-saving operating modes. The CPU and most peripherals are Halted. Select peripherals can continue to operate in Sleep mode and can be used to wake the device from Sleep. See the individual peripheral module sections for descriptions of behavior in Sleep.

Sleep mode includes the following characteristics:

- The CPU is halted
- The system clock source is typically shutdown. See **Section 26.3.3 "Peripheral Bus Scaling Method"** for specific information.
- There can be a wake-up delay based on the oscillator selection
- The Fail-Safe Clock Monitor (FSCM) does not operate during Sleep mode
- The BOR circuit remains operative during Sleep mode
- The WDT, if enabled, is not automatically cleared prior to entering Sleep mode
- Some peripherals can continue to operate at limited functionality in Sleep mode. These peripherals include I/O pins that detect a change in the input signal, WDT, ADC, UART and peripherals that use an external clock input or the internal LPRC oscillator (e.g., RTCC, Timer1 and Input Capture).
- I/O pins continue to sink or source current in the same manner as they do when the device is not in Sleep
- The USB module can override the disabling of the Posc or FRC. Refer to the USB section for specific details.
- Modules can be individually disabled by software prior to entering Sleep in order to further reduce consumption

The processor will exit, or 'wake-up', from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

26.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

Note 1: Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.

2: Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN (OSCCON<4>) bit is clear and a `WAIT` instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

26.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The Peripheral Bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as the USB, Interrupt Controller, DMA, and the bus matrix are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

REGISTER 27-6: DEVID: DEVICE AND REVISION ID REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0>(1)				DEVID<27:24>(1)			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16>(1)							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8>(1)							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0>(1)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-28 **VER<3:0>:** Revision Identifier bits(1)

bit 27-0 **DEVID<27:0>:** Device ID bits(1)

Note 1: See the *"PIC32 Flash Programming Specification"* (DS60001145) for a list of Revision and Device ID values.

TABLE 30-13: COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 4): 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage	—	±7.5	±25	mV	AVDD = VDD, AVSS = VSS
D301	VICM	Input Common Mode Voltage	0	—	VDD	V	AVDD = VDD, AVSS = VSS **(Note 2)**
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	Max VICM = (VDD - 1)V **(Note 2)**
D303A	TRESP	Large Signal Response Time	—	150	400	ns	AVDD = VDD, AVSS = VSS **(Note 1,2)**
D303B	TSRESP	Small Signal Response Time	—	1	—	μs	This is defined as an input step of 50 mV with 15 mV of overdrive **(Note 2)**
D304	ON2OV	Comparator Enabled to Output Valid	—	—	10	μs	Comparator module is configured before setting the comparator ON bit **(Note 2)**
D305	IVREF	Internal Voltage Reference	1.14	1.2	1.26	V	—
D312	TSET	Internal Comparator Voltage DRC Reference Setting time	—	—	10	μs	**(Note 3)**

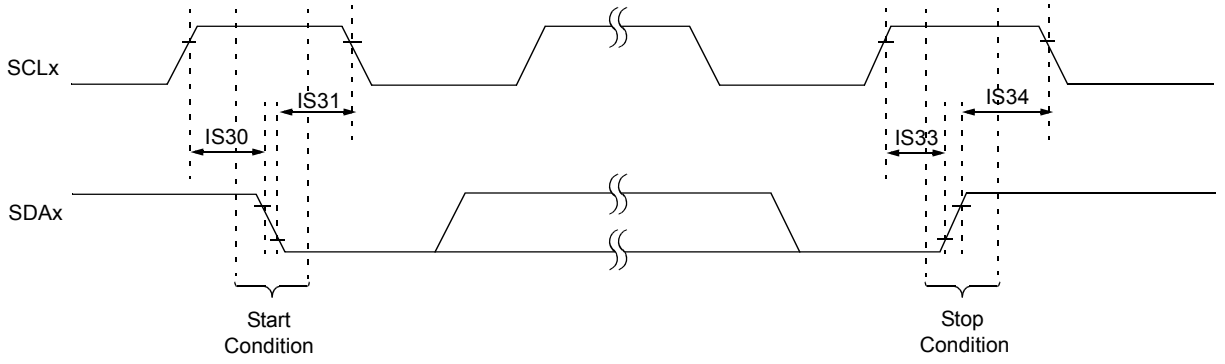
Note 1: Response time measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

2: These parameters are characterized but not tested.

3: Settling time measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but not tested in manufacturing.

4: The Comparator module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

FIGURE 30-16: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-17: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)

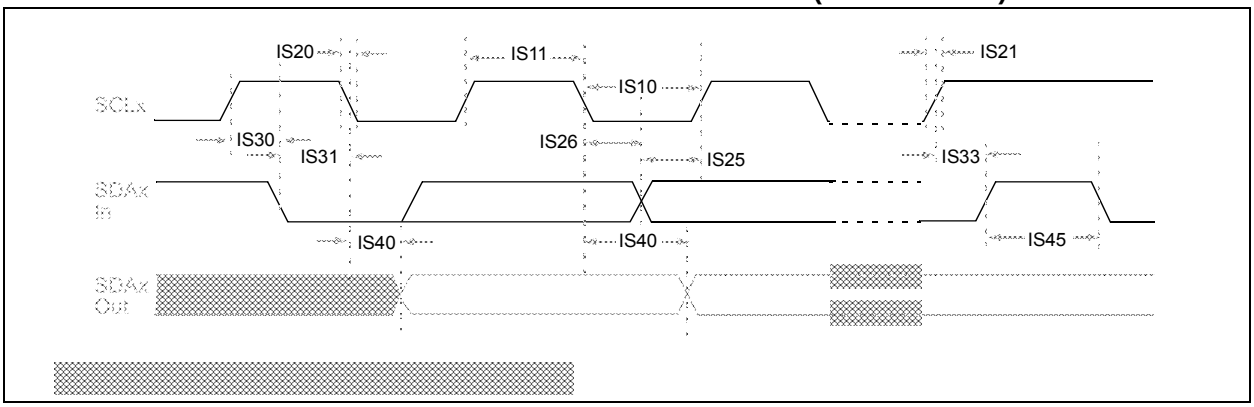


TABLE 30-36: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 4): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period(2)	65	—	—	ns	See Table 30-35
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed)	—	—	1000	ksps	AVDD = 3.0V to 3.6V
			—	—	400	ksps	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	1 TAD	—	—	—	TSAMP must be ≥ 132 ns
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger(3)	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1)(3)	—	0.5 TAD	—	—	—
AD63	TDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(3)	—	—	2	μs	—

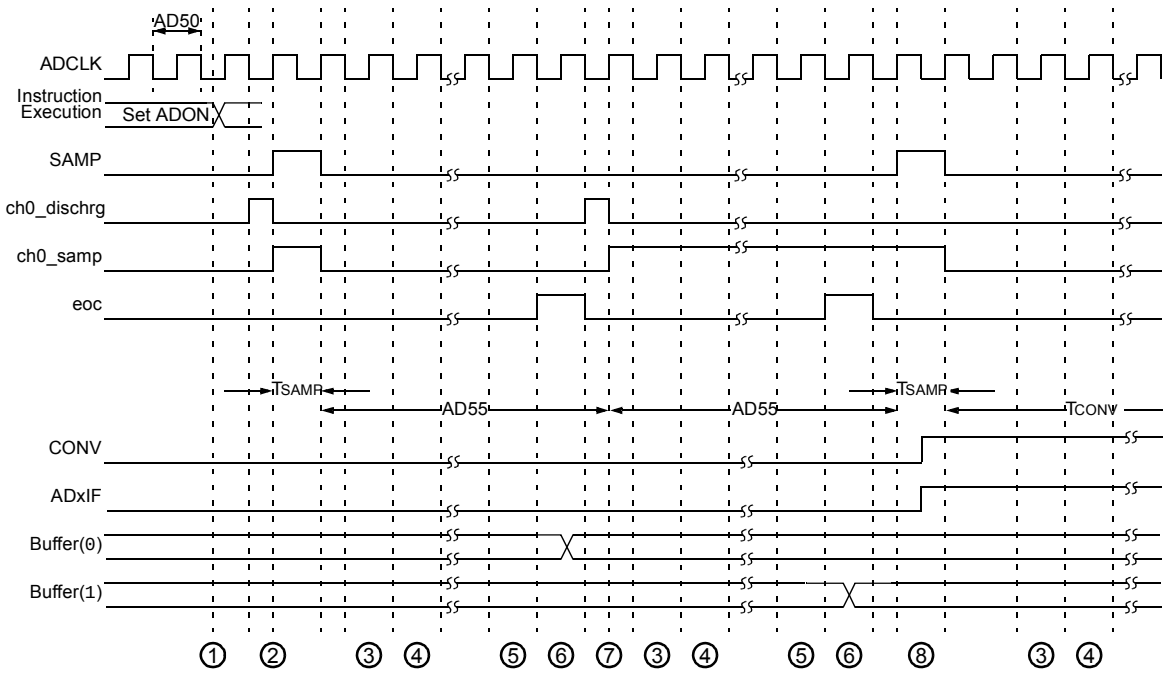
Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

3: Characterized by design but not tested.

4: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets ADxCON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104).

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.